



# 18Mb Pipelined DDR™II SIO SRAM Burst of 2

**IDT71P79204**  
**IDT71P79104**  
**IDT71P79804**  
**IDT71P79604**

## Features

- ◆ 18Mb Density (2Mx8, 2Mx9, 1Mx18, 512Kx36)
- ◆ Separate, Independent Read and Write Data Ports
  - Supports concurrent transactions
- ◆ Dual Echo Clock Output
- ◆ 2-Word Burst on all SRAM accesses
- ◆ Multiplexed Address Bus
  - One Read or one Write request per clock cycle
- ◆ DDR (Double Data Rate) Data Bus
  - Two word burst data per clock
- ◆ Depth expansion through Control Logic
- ◆ HSTL (1.5V) inputs that can be scaled to receive signals from 1.4V to 1.9V.
- ◆ Scalable output drivers
  - Can drive HSTL, 1.8V TTL or any voltage level from 1.4V to 1.9V.
  - Output Impedance adjustable from 35 ohms to 70 ohms
- ◆ 1.8V Core Voltage (VDD)
- ◆ 165-ball, 1.0mm pitch, 15mm x 17mm fBGA Package
- ◆ JTAG Interface

## Description

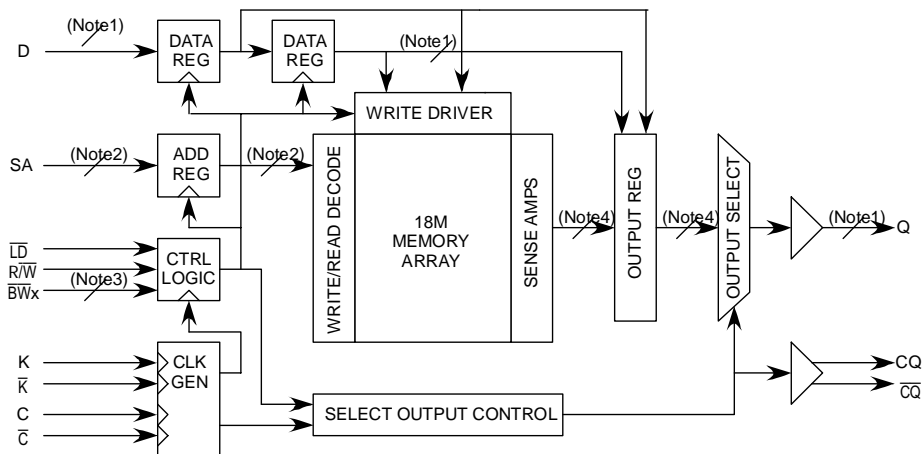
The IDT DDRII™ Burst of two SIO SRAMs are high-speed synchronous memories with independent, double-data-rate (DDR), read and write data ports with two data items passed with each read or write.

Using independent ports for read and write data access, simplifies system design by eliminating the need for bi-directional buses. All buses associated with the DDRII SIO are unidirectional and can be optimized for signal integrity at very high bus speeds. Memory bandwidth is higher than DDR SRAM with bi-directional data buses as separate read and write ports eliminate bus turn around cycle. Separate read and write ports also enable easy depth expansion. Each port can be selected independently with a  $\overline{R/W}$  input shared among all SRAMs and provide a new  $\overline{LD}$  load control signal for each bank. The DDRII SIO has scalable output impedance on its data output bus and echo clocks, allowing the user to tune the bus for low noise and high performance.

The DDRII SIO has a single SDR address bus with multiplexed read and write addresses. The read/write and load control inputs are received on the first half of the clock cycle. The byte and nibble write signals are received on both halves of the clock cycle simultaneously with the data they are controlling on the data input bus.

The DDRII SIO has echo clocks, which provide the user with a clock that is precisely timed to the data output, and tuned with matching impedance and signal quality. The user can use the echo clock for downstream clocking of the data. Echo clocks eliminate the need for the user to produce alternate clocks with precise timing, positioning, and signal qualities to guarantee data capture. Since the echo clocks are

## Functional Block Diagram



Notes:

- 1) Represents 8 data signal lines for x8, 9 signal lines for x9, 18 signal lines for x18, and 36 signal lines for x36
- 2) Represents 20 address signal lines for x8 and x9, 19 address signal lines for x18, and 18 address signal lines for x36.
- 3) Represents 1 signal line for x9, 2 signal lines for x18, and four signal lines for x36. On x8 parts, the  $\overline{BW}$  is a "nibble write" and there are 2 signal lines.
- 4) Represents 16 data signal lines for x8, 18 signal lines for x9, 36 signal lines for x18, and 72 signal lines for x36.

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generated by the same source that drives the data output, the relationship to the data is not significantly affected by voltage, temperature and process, as would be the case if the clock were generated by an outside source.

All interfaces of the DDR II SIO are HSTL, allowing speeds beyond SRAM devices that use any form of TTL interface. The interface can be scaled to higher voltages (up to 1.9V) to interface with 1.8V systems if necessary. The device has a  $V_{DDQ}$  and a separate  $V_{ref}$ , allowing the user to designate the interface operational voltage, independent of the device core voltage of 1.8V  $V_{DD}$ . The output impedance control allows the user to adjust the drive strength to adapt to a wide range of loads and transmission lines.

### Clocking

The DDRII SIO SRAM has two sets of input clocks, namely the  $K$ ,  $\bar{K}$  clocks and the  $C$ ,  $\bar{C}$  clocks. In addition, the DDRII SIO has an output "echo" clock,  $CQ$ ,  $\bar{CQ}$ .

The  $K$  and  $\bar{K}$  clocks are the primary device input clocks. The  $K$  clock is used to clock in the control signals ( $\bar{LD}$ ,  $R/\bar{W}$  and  $\bar{BW}x$  or  $\bar{NW}x$ ), the address, and the first word of the data burst during a write operation. The  $\bar{K}$  clock is used to clock in the control signals ( $\bar{BW}x$  or  $\bar{NW}x$ ) and the second word of the data burst during a write operation. The  $K$  and  $\bar{K}$  clocks are also used internally by the SRAM. In the event that the user disables the  $C$  and  $\bar{C}$  clocks, the  $K$  and  $\bar{K}$  clocks will also be used to clock the data out of the output register and generate the echo clocks.

The  $C$  and  $\bar{C}$  clocks may be used to clock the data out of the output register during read operations and to generate the echo clocks.  $C$  and  $\bar{C}$  must be presented to the SRAM within the timing tolerances. The output data from the DDRII SIO will be closely aligned to the  $C$  and  $\bar{C}$  input, through the use of an internal DLL. When  $C$  is presented to the DDRII SIO SRAM, the DLL will have already internally clocked the data to arrive at the device output simultaneously with the arrival of the  $\bar{C}$  clock. The  $C$  and second data item of the burst will also correspond.

### Single Clock Mode

The DDRII SIO SRAM may be operated with a single clock pair.  $C$  and  $\bar{C}$  may be disabled by tying both signals high, forcing the outputs and echo clocks to be controlled instead by the  $K$  and  $\bar{K}$  clocks.

### DLL Operation

The DLL in the output structure of the DDRII SIO SRAM can be used to closely align the incoming clocks  $C$  and  $\bar{C}$  with the output of the data, generating very tight tolerances between the two. The user may disable the DLL by holding  $\bar{Doff}$  low. With the DLL off, the  $C$  and  $\bar{C}$  (or  $K$  and  $\bar{K}$  if  $C$  and  $\bar{C}$  are not used) will directly clock the output register of the SRAM. With the DLL off, there will be a propagation delay from the time the clock enters the device until the data appears at the output.

### Echo Clock

The echo clocks,  $CQ$  and  $\bar{CQ}$ , are generated by the  $C$  and  $\bar{C}$  clocks (or  $K$ ,  $\bar{K}$  if  $C$ ,  $\bar{C}$  are disabled). The rising edge of  $C$  generates the rising edge of  $CQ$ , and the falling edge of  $\bar{C}$  generates the rising edge of  $\bar{CQ}$  and the falling edge of  $CQ$ . This scheme improves

the correlation of the rising and falling edges of the echo clock and will improve the duty cycle of the individual signals.

The echo clock is very closely aligned with the data, guaranteeing that the echo clock will remain closely correlated with the data, within the tolerances designated.

### Read and Write Operations

DDRII SIO devices internally store the two words of the burst as a single wide word and the words will retain their burst order. There is no ability to address an individual word level in a burst, as is possible in the DDRII common I/O devices. The byte and nibble write signals can be used to prevent writing to any individual bytes, or combined to prevent writing word(s) of the burst.

Read operations are initiated by holding Read/Write control input ( $R/\bar{W}$ ) high, the load control input ( $\bar{LD}$ ) low and presenting the read address to the address port during the rising edge of  $K$ , which will latch the address. The data will then be read and will appear at the device output at the designated time in correspondence with the  $C$  and  $\bar{C}$  clocks.

Write operations are initiated by holding the Read/Write control input ( $R/\bar{W}$ ) low, the load control input ( $\bar{LD}$ ) low and presenting the write address to the address port during the rising edge of  $K$ , which will latch the address. On the following rising edge of  $K$ , the first word of the two word burst must be present on the data input bus  $DQ[x:0]$ , along with the appropriate byte write or nibble write ( $\bar{BW}x$  or  $\bar{NW}x$ ) inputs. On the following rising edge of  $\bar{K}$ , the second half of the data write burst will be accepted at the device input with the designated ( $\bar{BW}x$  or  $\bar{NW}x$ ) inputs.

### Output Enables

The DDRII SIO SRAM automatically enables and disables the  $Q[x:0]$  outputs. When a valid read is in progress, and data is present at the output, the output will be enabled. If no valid data is present at the output (read not active), the output will be disabled (high impedance). The echo clocks will remain valid at all times and cannot be disabled or turned off. During power-up the  $Q$  outputs will come up in a high impedance state.

### Programmable Impedance

An external resistor,  $RQ$ , must be connected between the  $ZQ$  pin on the SRAM and  $V_{SS}$  to allow the SRAM to adjust its output drive impedance. The value of  $RQ$  must be 5X the value of the intended drive impedance of the SRAM. The allowable range of  $RQ$  to guarantee impedance matching with a tolerance of +/- 10% is between 175 ohms and 350 ohms, with  $V_{DDQ} = 1.5V$ . The output impedance is adjusted every 1024 clock cycles to correct for drifts in supply voltage and temperature. If the user wishes to drive the output impedance of the SRAM to its lowest value, the  $ZQ$  pin may be tied to  $V_{DDQ}$ .

## Pin Definitions

Symbol	Pin Function	Description
D[X:0]	Input Synchronous	Data input signals, sampled on the rising edge of K and $\bar{K}$ clocks during valid write operations 2M x 8 -- D[7:0] 2M x 9 -- D[8:0] 1M x 18 -- D[17:0] 512K x 36 -- D[35:0]
$\bar{B}W_0$ , $\bar{B}W_1$ $\bar{B}W_2$ , $\bar{B}W_3$	Input Synchronous	Byte Write Select 0, 1, 2, and 3 are active LOW. Sampled on the rising edge of the K and again on the rising edge of $\bar{K}$ clocks during write operations. Used to select which byte is written into the device during the current portion of the write operations. Bytes not written remain unaltered. All the byte writes are sampled on the same edge as the data. Deselecting a Byte Write Select will cause the corresponding byte of data to be ignored and not written in to the device. 2M x 9 -- $\bar{B}W_0$ controls DQ[8:0] 1M x 18 -- $\bar{B}W_0$ controls DQ[8:0] and $\bar{B}W_1$ controls DQ[17:9] 512K x 36 -- $\bar{B}W_0$ controls DQ[8:0], $\bar{B}W_1$ controls DQ[17:9], $\bar{B}W_2$ controls DQ[26:18] and $\bar{B}W_3$ controls DQ[35:27]
$\bar{N}W_0$ $\bar{N}W_1$	Input Synchronous	Nibble Write Select 0 and 1 are active LOW. Available only on x8 bit parts instead of Byte Write Selects. Sampled on the rising edge of the K and $\bar{K}$ clocks during write operations. Used to select which nibble is written into the device during the current portion of the write operations. Nibbles not written remain unaltered. All the nibble writes are sampled on the same edge as the data. Deselecting a Nibble Write Select will cause the corresponding nibble of data to be ignored and not written in to the device. 2M x 8-- $\bar{N}W_0$ controls D[3:0] and $\bar{N}W_1$ controls D[7:4]
SA	Input Synchronous	Address Inputs. Addresses are sampled on the rising edge of K clock during active read or write operations.
Q[X:0]	Output Synchronous	Data Output signals. These pins drive out the requested data during a Read operation. Valid data is driven out on the rising edge of both the C and $\bar{C}$ clocks during Read operations or K and $\bar{K}$ when operating in single clock mode. When the Read port is deselected, Q[X:0] are automatically three-stated.
$\bar{L}D$	Input Synchronous	Load Control Logic. Sampled on the rising edge of K. If $\bar{L}D$ is low, a two word burst read or write operation will be initiated as designated by the $R/\bar{W}$ input. If $\bar{L}D$ is high during the rising edge of K, operations in progress will complete, but new operations will not be initiated.
$R/\bar{W}$	Input Synchronous	Read or Write Control Logic. If $\bar{L}D$ is low during the rising edge of K, the $R/\bar{W}$ indicates whether a new operation should be a read or write. If $R/\bar{W}$ is high, a read operation will be initiated, if $R/\bar{W}$ is low, a write operation will be initiated. If the $\bar{L}D$ input is high during the rising edge of K, the $R/\bar{W}$ input will be ignored.
C	Input Clock	Positive Output Clock Input. C is used in conjunction with $\bar{C}$ to clock out the Read data from the device. C and $\bar{C}$ can be used together to deskew the flight times of various devices on the board back to the controller. See application example for further details.
$\bar{C}$	Input Clock	Negative Output Clock Input. $\bar{C}$ is used in conjunction with C to clock out the Read data from the device. C and $\bar{C}$ can be used together to deskew the flight times of various devices on the board back to the controller. See application example for further details.
K	Input Clock	Positive Input Clock Input. The rising edge of K is used to capture synchronous inputs to the device and to drive out data through Q[X:0] when in single clock mode. All accesses are initiated on the rising edge of K.
$\bar{K}$	Input Clock	Negative Input Clock Input. $\bar{K}$ is used to capture synchronous inputs being presented to the device and to drive out data through Q[X:0] when in single clock mode.
$CQ$ , $\bar{C}Q$	Output Clock	Synchronous Echo clock outputs. The rising edges of these outputs are tightly matched to the synchronous data outputs and can be used as a data valid indication. These signals are free running and do not stop when the output data is three stated.
ZQ	Input	Output Impedance Matching Input. This input is used to tune the device outputs to the system data bus impedance. Q[X:0] output impedance is set to $0.2 \times RQ$ , where RQ is a resistor connected between ZQ and ground. Alternately, this pin can be connected directly to VDDQ, which enables the minimum impedance mode. This pin cannot be connected directly to GND or left unconnected.

## Pin Definitions continued

Symbol	Pin Function	Description
$\overline{\text{Doff}}$	Input	DLL Turn Off. When low this input will turn off the DLL inside the device. The AC timings with the DLL turned off will be different from those listed in this data sheet. There will be an increased propagation delay from the incidence of C and $\overline{\text{C}}$ to Q, or K and $\overline{\text{K}}$ to Q as configured. The propagation delay is not a tested parameter, but will be similar to the propagation delay of other SRAM devices in this speed grade.
TDO	Output	TDO pin for JTAG.
TCK	Input	TCK pin for JTAG.
TDI	Input	TDI pin for JTAG. An internal resistor will pull TDI to VDD when the pin is unconnected.
TMS	Input	TMS pin for JTAG. An internal resistor will pull TMS to VDD when the pin is unconnected.
NC		No connects inside the package. Can be tied to any voltage level.
VREF	Input Reference	Reference Voltage input. Static input used to set the reference level for HSTL inputs and Outputs as well as AC measurement points.
VDD	Power Supply	Power supply inputs to the core of the device. Should be connected to a 1.8V power supply.
VSS	Ground	Ground for the device. Should be connected to ground of the system.
VDDQ	Power Supply	Power supply for the outputs of the device. Should be connected to a 1.5V power supply for HSTL or scaled to the desired output voltage.

6432 tbl 02b

## Pin Configuration IDT71P79204 (2M x 8)

	1	2	3	4	5	6	7	8	9	10	11
A	$\overline{\text{CQ}}$	VSS/ SA <sup>(2)</sup>	SA	$\overline{\text{R/W}}$	$\overline{\text{NW}}_1$	$\overline{\text{K}}$	NC	$\overline{\text{LD}}$	SA	VSS/ SA <sup>(1)</sup>	CQ
B	NC	NC	NC	SA	NC	K	$\overline{\text{NW}}_0$	SA	NC	NC	Q3
C	NC	NC	NC	VSS	SA	SA	SA	VSS	NC	NC	D3
D	NC	D4	NC	VSS	VSS	VSS	VSS	VSS	NC	NC	NC
E	NC	NC	Q4	VDDQ	VSS	VSS	VSS	VDDQ	NC	D2	Q2
F	NC	NC	NC	VDDQ	VDD	VSS	VDD	VDDQ	NC	NC	NC
G	NC	D5	Q5	VDDQ	VDD	VSS	VDD	VDDQ	NC	NC	NC
H	$\overline{\text{Doff}}$	VREF	VDDQ	VDDQ	VDD	VSS	VDD	VDDQ	VDDQ	VREF	ZQ
J	NC	NC	NC	VDDQ	VDD	VSS	VDD	VDDQ	NC	Q1	D1
K	NC	NC	NC	VDDQ	VDD	VSS	VDD	VDDQ	NC	NC	NC
L	NC	Q6	D6	VDDQ	VSS	VSS	VSS	VDDQ	NC	NC	Q0
M	NC	NC	NC	VSS	VSS	VSS	VSS	VSS	NC	NC	D0
N	NC	D7	NC	VSS	SA	SA	SA	VSS	NC	NC	NC
P	NC	NC	Q7	SA	SA	C	SA	SA	NC	NC	NC
R	TDO	TCK	SA	SA	SA	$\overline{\text{C}}$	SA	SA	SA	TMS	TDI

6432 tbl 12

### 165-ball FBGA Pinout TOP VIEW

**NOTES:**

1. A10 is reserved for the 36Mb expansion address.
2. A2 is reserved for the 72Mb expansion address.

## Pin Configuration IDT71P79104 (2M x 9)

	1	2	3	4	5	6	7	8	9	10	11
A	$\overline{CQ}$	V <sub>SS</sub> /SA <sup>(2)</sup>	SA	$\overline{R/W}$	NC	$\overline{K}$	NC	$\overline{LD}$	SA	V <sub>SS</sub> /SA <sup>(1)</sup>	CQ
B	NC	NC	NC	SA	NC	K	$\overline{BW}$	SA	NC	NC	Q <sub>3</sub>
C	NC	NC	NC	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	NC	D <sub>3</sub>
D	NC	D <sub>4</sub>	NC	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	NC
E	NC	NC	Q <sub>4</sub>	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	D <sub>2</sub>	Q <sub>2</sub>
F	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
G	NC	D <sub>5</sub>	Q <sub>5</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
H	$\overline{Doff}$	V <sub>REF</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	V <sub>DDQ</sub>	V <sub>REF</sub>	ZQ
J	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	Q <sub>1</sub>	D <sub>1</sub>
K	NC	NC	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	NC	NC
L	NC	Q <sub>6</sub>	D <sub>6</sub>	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	NC	Q <sub>0</sub>
M	NC	NC	NC	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	NC	NC	D <sub>0</sub>
N	NC	D <sub>7</sub>	NC	V <sub>SS</sub>	SA	SA	SA	V <sub>SS</sub>	NC	NC	NC
P	NC	NC	Q <sub>7</sub>	SA	SA	C	SA	SA	NC	D <sub>8</sub>	Q <sub>8</sub>
R	TDO	TCK	SA	SA	SA	$\overline{C}$	SA	SA	SA	TMS	TDI

6432 tbl 12a

### 165-ball FBGA Pinout Top View

**NOTES:**

1. A10 is reserved for the 36Mb expansion address.
2. A2 is reserved for the 72Mb expansion address.

## Pin Configuration IDT71P79804 (1M x 18)

	1	2	3	4	5	6	7	8	9	10	11
A	$\overline{CQ}$	Vss/ SA <sup>(3)</sup>	NC/ SA <sup>(1)</sup>	R $\overline{W}$	$\overline{BW1}$	$\overline{K}$	NC	$\overline{LD}$	SA	Vss/ SA <sup>(2)</sup>	CQ
B	NC	Q9	D9	SA	NC	K	$\overline{BW0}$	SA	NC	NC	Q8
C	NC	NC	D10	Vss	SA	SA	SA	Vss	NC	Q7	D8
D	NC	D11	Q10	Vss	Vss	Vss	Vss	Vss	NC	NC	D7
E	NC	NC	Q11	VDDQ	Vss	Vss	Vss	VDDQ	NC	D6	Q6
F	NC	Q12	D12	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	Q5
G	NC	D13	Q13	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	D5
H	$\overline{Doff}$	VREF	VDDQ	VDDQ	VDD	Vss	VDD	VDDQ	VDDQ	VREF	ZQ
J	NC	NC	D14	VDDQ	VDD	Vss	VDD	VDDQ	NC	Q4	D4
K	NC	NC	Q14	VDDQ	VDD	Vss	VDD	VDDQ	NC	D3	Q3
L	NC	Q15	D15	VDDQ	Vss	Vss	Vss	VDDQ	NC	NC	Q2
M	NC	NC	D16	Vss	Vss	Vss	Vss	Vss	NC	Q1	D2
N	NC	D17	Q16	Vss	SA	SA	SA	Vss	NC	NC	D1
P	NC	NC	Q17	SA	SA	C	SA	SA	NC	D0	Q0
R	TDO	TCK	SA	SA	SA	$\overline{C}$	SA	SA	SA	TMS	TDI

6432 tbl 12b

### 165-ball FBGA Pinout Top View

NOTES:

1. A3 is reserved for the 36Mb expansion address.
2. A10 is reserved for the 72Mb expansion address. This must be tied or driven to VSS on the 1M x 18 DDRII SIO Burst of 2 (71P79804) devices.
3. A2 is reserved for the 144Mb expansion address. This must be tied or driven to VSS on the 1M x 18 DDRII SIO Burst of 2 (71P79804) devices.

## Pin Configuration IDT71P79604 (512K x 36)

	1	2	3	4	5	6	7	8	9	10	11
A	$\overline{\text{CQ}}$	VSS/ SA <sup>(4)</sup>	NC/ SA <sup>(2)</sup>	$\overline{\text{R/W}}$	$\overline{\text{BW}}_2$	$\overline{\text{K}}$	$\overline{\text{BW}}_1$	$\overline{\text{LD}}$	NC/ SA <sup>(1)</sup>	VSS/ SA <sup>(3)</sup>	CQ
B	Q27	Q18	D18	SA	$\overline{\text{BW}}_3$	K	$\overline{\text{BW}}_0$	SA	D17	Q17	Q8
C	D27	Q28	D19	VSS	SA	SA	SA	VSS	D16	Q7	D8
D	D28	D20	Q19	VSS	VSS	VSS	VSS	VSS	Q16	D15	D7
E	Q29	D29	Q20	VDDQ	VSS	VSS	VSS	VDDQ	Q15	D6	Q6
F	Q30	Q21	D21	VDDQ	VDD	VSS	VDD	VDDQ	D14	Q14	Q5
G	D30	D22	Q22	VDDQ	VDD	VSS	VDD	VDDQ	Q13	D13	D5
H	$\overline{\text{Doff}}$	VREF	VDDQ	VDDQ	VDD	VSS	VDD	VDDQ	VDDQ	VREF	ZQ
J	D31	Q31	D23	VDDQ	VDD	VSS	VDD	VDDQ	D12	Q4	D4
K	Q32	D32	Q23	VDDQ	VDD	VSS	VDD	VDDQ	Q12	D3	Q3
L	Q33	Q24	D24	VDDQ	VSS	VSS	VSS	VDDQ	D11	Q11	Q2
M	D33	Q34	D25	VSS	VSS	VSS	VSS	VSS	D10	Q1	D2
N	D34	D26	Q25	VSS	SA	SA	SA	VSS	Q10	D9	D1
P	Q35	D35	Q26	SA	SA	C	SA	SA	Q9	D0	Q0
R	TDO	TCK	SA	SA	SA	$\overline{\text{C}}$	SA	SA	SA	TMS	TDI

6432 tbl 12c

### 165-ball FBGA Pinout TOP VIEW

#### NOTES:

1. A9 is reserved for the 36Mb expansion address.
2. A3 is reserved for the 72Mb expansion address.
3. A10 is reserved for the 144Mb expansion address. This must be tied or driven to VSS on the 512K x 36 DDRII SIO Burst of 2 (71P79604) devices.
4. A2 is reserved for the 288Mb expansion address. This must be tied or driven to VSS on the 512K x 36 DDRII SIO Burst of 2 (71P79604) devices.



## Absolute Maximum Ratings<sup>(1) (2)</sup>

Symbol	Rating	Value	Unit
V <sub>TERM</sub>	Supply Voltage on V <sub>DD</sub> with Respect to GND	-0.5 to +2.9	V
V <sub>TERM</sub>	Supply Voltage on V <sub>DDQ</sub> with Respect to GND	-0.5 to V <sub>DD</sub> +0.3	V
V <sub>TERM</sub>	Voltage on Input terminals with respect to GND	-0.5 to V <sub>DD</sub> +0.3	V
V <sub>TERM</sub>	Voltage on output and I/O terminals with respect to GND	-0.5 to V <sub>DDQ</sub> +0.3	
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
I <sub>OUT</sub>	Continuous Current into Outputs	± 20	mA

6432 tbl 05

### Notes:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V<sub>DDQ</sub> must not exceed V<sub>DD</sub> during normal operation.

## Write Descriptions<sup>(1,2)</sup>

Signal	$\overline{BW}_0$	$\overline{BW}_1$	$\overline{BW}_2$	$\overline{BW}_3$	$\overline{NW}_0$	$\overline{NW}_1$
Write Byte 0	L	X	X	X	X	X
Write Byte 1	X	L	X	X	X	X
Write Byte 2	X	X	L	X	X	X
Write Byte 3	X	X	X	L	X	X
Write Nibble 0	X	X	X	X	L	X
Write Nibble 1	X	X	X	X	X	L

6432 tbl 09

### Notes:

- All byte write ( $\overline{BW}_x$ ) and nibble write ( $\overline{NW}_x$ ) signals are sampled on the rising edge of K and again on  $\overline{K}$ . The data that is present on the data bus in the designated byte/nibble will be latched into the input if the corresponding  $\overline{BW}_x$  or  $\overline{NW}_x$  is held low. The rising edge of K will sample the first byte/nibble of the two word burst and the rising edge of  $\overline{K}$  will sample the second byte/nibble of the two word burst.
- The availability of the  $\overline{BW}_x$  or  $\overline{NW}_x$  on designated devices is described in the pin description table.
- The DDRII SIO Burst of two SRAM has data forwarding. A read request that is initiated on cycle following a write request to the same address will produce the newly written data in response to the read request.

## Capacitance (TA = +25°C, f = 1.0MHz)<sup>(1)</sup>

Symbol	Parameter	Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>DD</sub> = 1.8V V <sub>DDQ</sub> = 1.5V	5	pF
C <sub>CLK</sub>	Clock Input Capacitance		6	pF
C <sub>O</sub>	Output Capacitance		7	pF

### Note:

6432 tbl 06

- Tested at characterization and retested after any design or process change that may affect these parameters.

## Recommended DC Operating Conditions

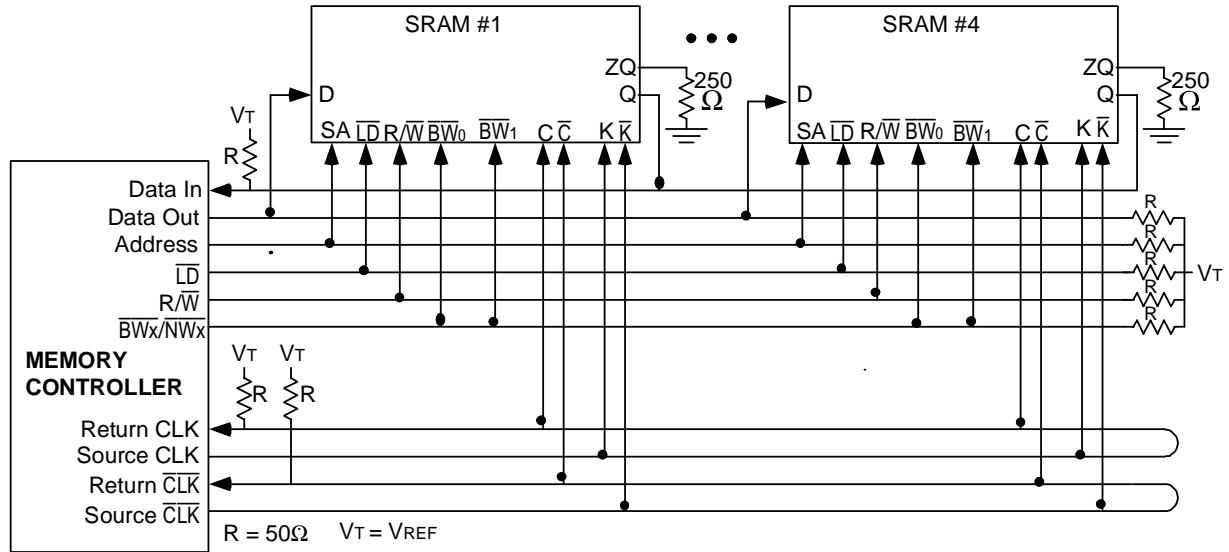
Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>DD</sub>	Power Supply Voltage	1.7	1.8	1.9	V
V <sub>DDQ</sub>	I/O Supply Voltage	1.4	1.5	1.9	V
V <sub>SS</sub>	Ground	0	0	0	V
V <sub>REF</sub>	Input Reference Voltage	-	V <sub>DDQ</sub> /2	-	V
T <sub>A</sub>	Ambient Temperature <sup>(1)</sup>	Commercial	0 to +70		°C
		Industrial	-40 to +85		°C

### Note:

6432 tbl 04

- During production testing, the case temperature equals the ambient temperature.

## Application Example



6432 drw 20

## DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ( $V_{DD} = 1.8 \pm 100\text{mV}$ , $V_{DDQ} = 1.4\text{V to }1.9\text{V}$ )

Parameter	Symbol	Test Conditions	Min	Max	Unit	Note	
Input Leakage Current	IIL	$V_{DD} = \text{Max } V_{IN} = V_{SS} \text{ to } V_{DDQ}$	-2	+2	$\mu\text{A}$		
Output Leakage Current	IOL	Output Disabled	-2	+2	$\mu\text{A}$		
				Com'l	Ind		
Operating Current (x36): DDR	I <sub>DD</sub>	$V_{DD} = \text{Max}$ , I <sub>OUT</sub> = 0mA (outputs open), Cycle Time $\geq$ t <sub>CKKH</sub> Min	250MHz	-	1050	1100	mA 1
			200MHz	-	950	1000	
			167MHz	-	850	900	
Operating Current (x18): DDR	I <sub>DD</sub>	$V_{DD} = \text{Max}$ , I <sub>OUT</sub> = 0mA (outputs open), Cycle Time $\geq$ t <sub>CKKH</sub> Min	267MHz	-	950	980	mA 1
			250MHz	-	850	900	
			200MHz	-	750	800	
			167MHz	-	650	700	
Operating Current (x9,x8): DDR	I <sub>DD</sub>	$V_{DD} = \text{Max}$ , I <sub>OUT</sub> = 0mA (outputs open), Cycle Time $\geq$ t <sub>CKKH</sub> Min	250MHz	-	800	850	mA 1
			200MHz	-	700	750	
			167MHz	-	600	650	
Standby Current: NOP	I <sub>SB1</sub>	Device Deselected (in NOP state) I <sub>OUT</sub> = 0mA (outputs open), f=Max, All Inputs $\leq 0.2\text{V}$ or $\geq V_{DD} - 0.2\text{V}$	267MHz	-	420	450	mA 2
			250MHz	-	375	410	
			200MHz	-	335	370	
			167MHz	-	300	335	
Output High Voltage	V <sub>OH1</sub>	R <sub>Q</sub> = 250 $\Omega$ , I <sub>OH</sub> = -15mA	$V_{DDQ}/2-0.12$	$V_{DDQ}/2+0.12$	V	3,7	
Output Low Voltage	V <sub>OL1</sub>	R <sub>Q</sub> = 250 $\Omega$ , I <sub>OL</sub> = 15mA	$V_{DDQ}/2-0.12$	$V_{DDQ}/2+0.12$	V	4,7	
Output High Voltage	V <sub>OH2</sub>	I <sub>OH</sub> = -0.1mA	$V_{DDQ}-0.2$	$V_{DDQ}$	V	5	
Output Low Voltage	V <sub>OL2</sub>	I <sub>OL</sub> = 0.1mA	V <sub>SS</sub>	0.2	V	6	

6432 tbl 10c

### NOTES:

- Operating Current is calculated with 50% read cycles and 50% write cycles.
- Standby Current is only after all pending read and write burst operations are completed.
- Outputs are impedance-controlled.  $I_{OH} = -(V_{DDQ}/2)/(R_Q/5)$  and is guaranteed by device characterization for  $175\Omega \leq R_Q < 350\Omega$ . This parameter is tested at  $R_Q = 250\Omega$ , which gives a nominal 50 $\Omega$  output impedance.
- Outputs are impedance-controlled.  $I_{OL} = (V_{DDQ}/2)/(R_Q/5)$  and is guaranteed by device characterization for  $175\Omega \leq R_Q < 350\Omega$ . This parameter is tested at  $R_Q = 250\Omega$ , which gives a nominal 50 $\Omega$  output impedance.
- This measurement is taken to ensure that the output has the capability of pulling to the  $V_{DDQ}$  rail, and is not intended to be used as an impedance measurement point.
- This measurement is taken to ensure that the output has the capability of pulling to  $V_{SS}$ , and is not intended to be used as an impedance measurement point.
- Programmable Impedance Mode.

## Input Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ( $V_{DD} = 1.8 \pm 100\text{mV}$ , $V_{DDQ} = 1.4\text{V to } 1.9\text{V}$ )

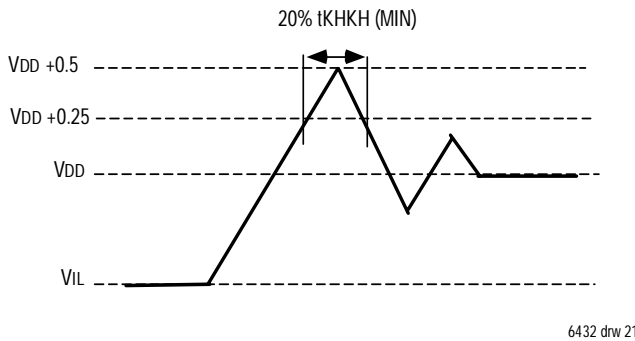
Parameter	Symbol	Min	Max	Unit	Notes
Input High Voltage, DC	$V_{IH} (DC)$	$V_{REF} + 0.1$	$V_{DDQ} + 0.3$	V	1,2
Input Low Voltage, DC	$V_{IL} (DC)$	-0.3	$V_{REF} - 0.1$	V	1,3
Input High Voltage, AC	$V_{IH} (AC)$	$V_{REF} + 0.2$	-	V	4,5
Input Low Voltage, AC	$V_{IL} (AC)$	-	$V_{REF} - 0.2$	V	4,5

**NOTES:**

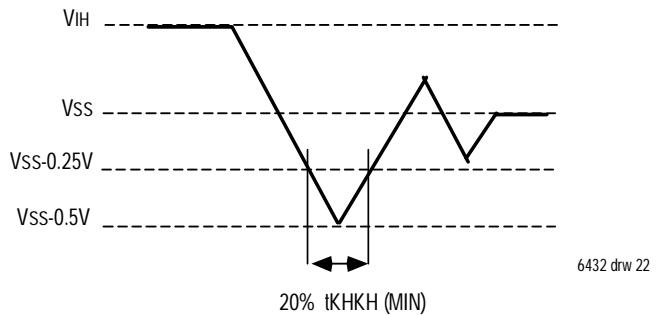
6432 tbl 10d

- These are DC test criteria. DC design criteria is  $V_{REF} \pm 50\text{mV}$ . The AC  $V_{IH}/V_{IL}$  levels are defined separately for measuring timing parameters.
- $V_{IH} (Max) DC = V_{DDQ} + 0.3$ ,  $V_{IH} (Max) AC = V_{DD} + 0.5\text{V}$  (pulse width  $\leq 20\%$  tKHKH (min))
- $V_{IL} (Min) DC = -0.3\text{V}$ ,  $V_{IL} (Min) AC = -0.5\text{V}$  (pulse width  $\leq 20\%$  tKHKH (min))
- This condition is for AC function test only, not for AC parameter test.
- To maintain a valid level, the transitioning edge of the input must:
  - Sustain a constant slew rate from the current AC level through the target AC level,  $V_{IL}(AC)$  or  $V_{IH}(AC)$
  - Reach at least the target AC level.
  - After the AC target level is reached, continue to maintain at least the target DC level,  $V_{IL}(DC)$  or  $V_{IH}(DC)$

### Overshoot Timing



### Undershoot Timing



## AC Test Conditions

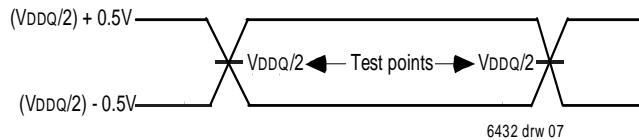
Parameter	Symbol	Value	Unit
Core Power Supply Voltage	V <sub>DD</sub>	1.7-1.9	V
Output Power Supply Voltage	V <sub>DDQ</sub>	1.4-1.9	V
Input High Level	V <sub>IH</sub>	(V <sub>DDQ</sub> /2) + 0.5	V
Input Low Level	V <sub>IL</sub>	(V <sub>DDQ</sub> /2) - 0.5	V
Input Reference Level	V <sub>REF</sub>	V <sub>DDQ</sub> /2	V
Input Rise/Fall Time	T <sub>R</sub> /T <sub>F</sub>	0.3/0.3	ns
Output Timing Reference Level		V <sub>DDQ</sub> /2	V

**NOTE:**

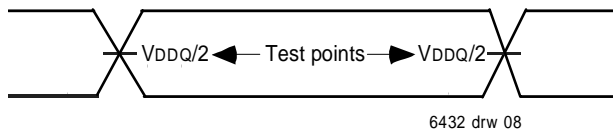
6432 tbl 11a

- Parameters are tested with R<sub>Q</sub>=250Ω

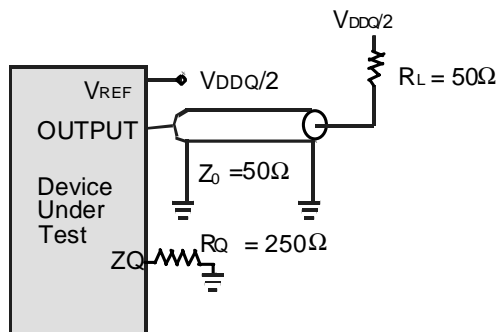
## Input Waveform



## Output Waveform



## AC Test Loads



## AC Electrical Characteristics

(VDD = 1.8 ± 100mV, VDDQ = 1.4V to 1.9V, Commercial and Industrial Temperature Ranges)<sup>(3,7)</sup>

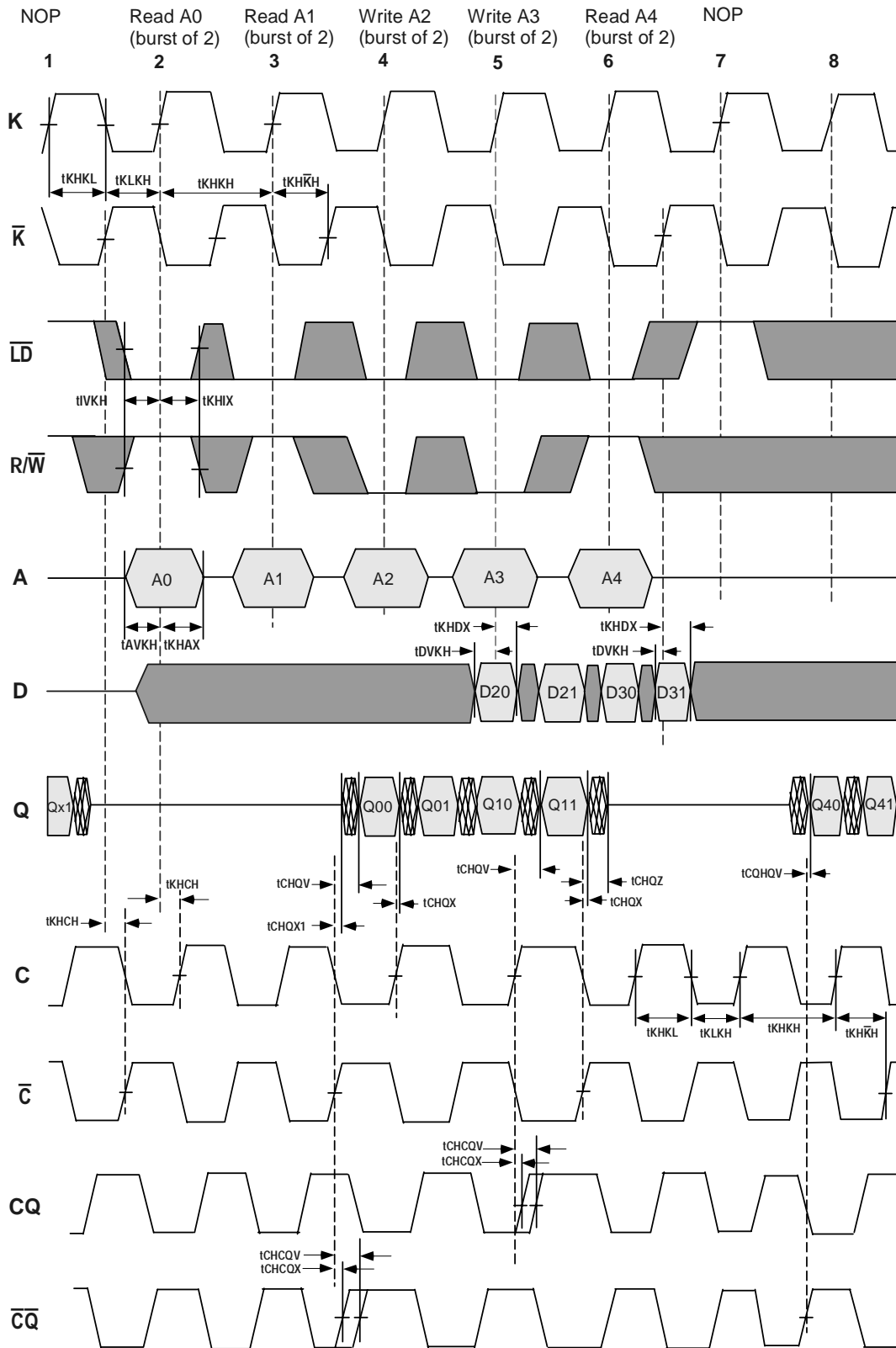
Symbol	Parameter	267MHz		250MHz		200MHz		167MHz		Unit	Notes
		Min.	Max	Min.	Max	Min.	Max	Min.	Max		
<b>Clock Parameters</b>											
t <sub>KHKH</sub>	Clock Cycle Time (K, $\bar{K}$ , C, $\bar{C}$ )	3.75	6.30	4.00	6.30	5.00	7.88	6.00	8.40	ns	
t <sub>KC var</sub>	Clock Phase Jitter (K, $\bar{K}$ , C, $\bar{C}$ )	-	-	-	0.20	-	0.20	-	0.20	ns	1,5
t <sub>KHKL</sub>	Clock High Time (K, $\bar{K}$ , C, $\bar{C}$ )	1.50	-	1.60	-	2.00	-	2.40	-	ns	8
t <sub>KLKH</sub>	Clock LOW Time (K, $\bar{K}$ , C, $\bar{C}$ )	1.50	-	1.60	-	2.00	-	2.40	-	ns	8
t <sub>KH<math>\bar{K}</math>H</sub>	Clock to $\bar{C}$ lock (K → $\bar{K}$ , C → $\bar{C}$ )	1.69	-	1.80	-	2.20	-	2.70	-	ns	9
t $\bar{K}$ HKH	$\bar{C}$ lock to clock ( $\bar{K}$ → K, $\bar{C}$ → C)	1.69	-	1.80	-	2.20	-	2.70	-	ns	9
t <sub>KHCH</sub>	Clock to data clock (K → C, $\bar{K}$ → $\bar{C}$ )	0.00	1.69	0.00	1.80	0.00	2.30	0.00	2.80	ns	
t <sub>KC lock</sub>	DLL lock time (K, C)	1024	-	1024	-	1024	-	1024	-	cycles	2
t <sub>KC reset</sub>	K static to DLL reset	30	-	30	-	30	-	30	-	ns	
<b>Output Parameters</b>											
t <sub>CHOV</sub>	C, $\bar{C}$ HIGH to output valid	-	0.45	-	0.45	-	0.45	-	0.50	ns	3
t <sub>CHOX</sub>	C, $\bar{C}$ HIGH to output hold	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3
t <sub>CHCOV</sub>	C, $\bar{C}$ HIGH to echo clock valid	-	0.45	-	0.45	-	0.45	-	0.50	ns	3
t <sub>CHCOX</sub>	C, $\bar{C}$ HIGH to echo clock hold	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3
t <sub>CQHOV</sub>	CQ, $\bar{C}Q$ HIGH to output valid	-	0.30	-	0.30	-	0.35	-	0.40	ns	
t <sub>CQHOX</sub>	CQ, $\bar{C}Q$ HIGH to output hold	-0.30	-	-0.30	-	-0.35	-	-0.40	-	ns	
t <sub>CHOZ</sub>	C HIGH to output High-Z	-	0.45	-	0.45	-	0.45	-	0.50	ns	3,4,5
t <sub>CHOX1</sub>	C HIGH to output Low-Z	-0.45	-	-0.45	-	-0.45	-	-0.50	-	ns	3,4,5
<b>Set-Up Times</b>											
t <sub>AVKH</sub>	Address valid to K, $\bar{K}$ rising edge	0.50	-	0.50	-	0.60	-	0.70	-	ns	6
t <sub>IVKH</sub>	R/ $\bar{W}$ inputs valid to K, $\bar{K}$ rising edge	0.50	-	0.50	-	0.60	-	0.70	-	ns	
t <sub>DVKH</sub>	Data-in and $\bar{B}Wx/\bar{N}Wx$ valid to K, $\bar{K}$ rising edge	0.35	-	0.35	-	0.40	-	0.50	-	ns	
<b>Hold Times</b>											
t <sub>KHAX</sub>	K, $\bar{K}$ rising edge to address hold	0.50	-	0.50	-	0.60	-	0.70	-	ns	6
t <sub>KHIX</sub>	K, $\bar{K}$ rising edge to R/ $\bar{W}$ inputs hold	0.50	-	0.50	-	0.60	-	0.70	-	ns	
t <sub>KHDX</sub>	K, $\bar{K}$ rising edge to data-in and $\bar{B}Wx/\bar{N}Wx$ hold	0.35	-	0.35	-	0.40	-	0.50	-	ns	

6432 tbl 11

### NOTES:

- Clock phase jitter is the variance from clock rising edge to the next expected clock rising edge.
- V<sub>dd</sub> slew rate must be less than 0.1V DC per 50 ns for DLL lock retention. DLL lock time begins once V<sub>dd</sub> and input clock are stable.
- If C,  $\bar{C}$  are tied High, K,  $\bar{K}$  become the references for C,  $\bar{C}$  timing parameters.
- To avoid bus contention, at a given voltage and temperature t<sub>CHQX1</sub> is bigger than t<sub>CHQZ</sub>. The specs as shown do not imply bus contention because t<sub>CHQX1</sub> is a MIN parameter that is worse case at totally different test conditions (0°C, 1.9V) than t<sub>CHQZ</sub>, which is a MAX parameter (worst case at 70°C, 1.7V) It is not possible for two SRAMs on the same board to be at such different voltage and temperature.
- This parameter is guaranteed by device characterization, but not production tested.
- All address inputs must meet the specified setup and hold times for all latching clock edges.
- During production testing, the case temperature equals TA.
- Clock High Time (t<sub>KHKL</sub>) and Clock Low Time (t<sub>KLKH</sub>) should be within 40% to 60% of the cycle time (t<sub>KHKH</sub>).
- Clock to clock time (t<sub>KHKH</sub>) and Clock to clock time (t<sub>KHKH</sub>) should be within 45% to 55% of the cycle time (t<sub>KHKH</sub>).

## Timing Waveform of Combined Read and Write Cycles



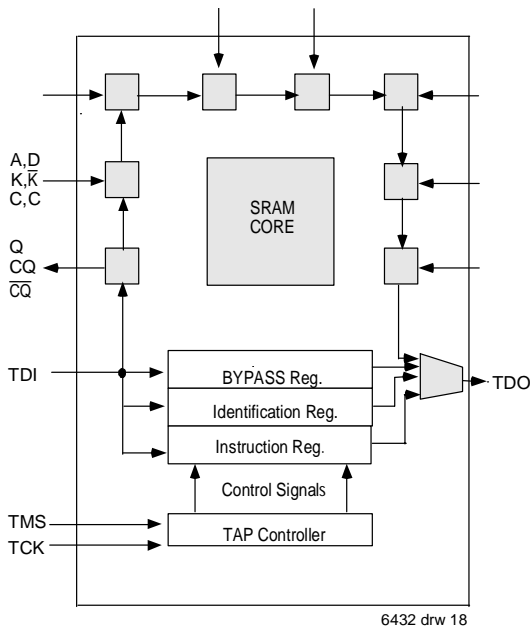
6432 drw 09a

## IEEE 1149.1 TEST ACCESS PORT AND BOUNDARY SCAN-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port (TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up; therefore, the TRST signal is not

required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to VSS to preclude a mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected, but they may also be tied to VDD through a resistor. TDO should be left unconnected.

### JTAG Block Diagram



### JTAG Instruction Coding

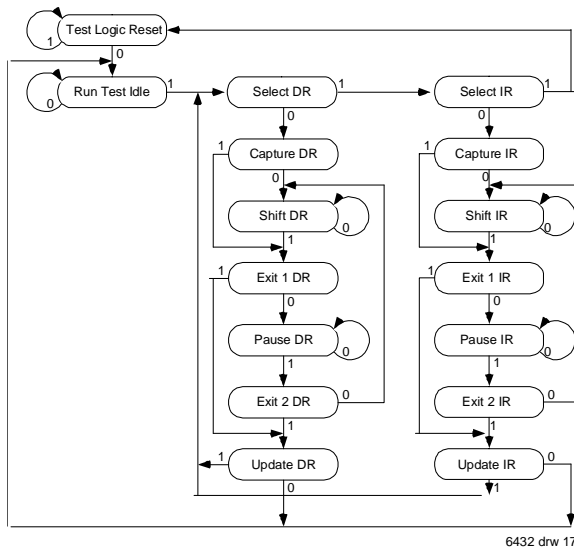
IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	EXTEST	Boundary Scan Register	
0	0	1	IDCODE	Identification register	2
0	1	0	SAMPLE-Z	Boundary Scan Register	1
0	1	1	RESERVED	Do Not Use	5
1	0	0	SAMPLE/PRELOAD	Boundary Scan register	4
1	0	1	RESERVED	Do Not Use	5
1	1	0	RESERVED	Do Not Use	5
1	1	1	BYPASS	Bypass Register	3

#### NOTES:

6432 tbl 13

1. Places Qs in Hi-Z in order to sample all input data regardless of other SRAM inputs.
2. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.
3. Bypass register is initialized to Vss when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when existing the Shift DR states.
4. SAMPLE instruction does not place output pins in Hi-Z.
5. This instruction is reserved for future use.

### TAP Controller State Diagram





### Scan Register Definition

Part	Instrustion Register	Bypass Register	ID Register	Boundry Scan
512K x36	3 bits	1 bit	32 bits	107 bits
1Mx18	3 bits	1 bit	32 bits	107 bits
2Mx8/x9	3 bits	1 bit	32 bits	107 bits

6432 tbl 14

### Identification Register Definitions

INSTRUCTION FIELD	ALL DEVICES	DESCRIPTION	PART NUMBER
Revision Number (31:29)	0x0	Revision Number	
Device ID (28:12)	0x0298 0x0299 0x029A 0x029B	512Kx36 1Mx18 2Mx9 2Mx8	DDRII SIO BURST OF 2 71P79604S 71P79804S 71P79104S 71P79204S
IDT JEDEC ID CODE (11:1)	0x033	Allows unique identification of SRAM vendor.	
ID Register Presence Indicator (0)	1	Indicates the presence of an ID register.	

6432 tbl 15

## Boundary Scan Exit Order

ORDER	PIN ID
1	6R
2	6P
3	6N
4	7P
5	7N
6	7R
7	8R
8	8P
9	9R
10	11P
11	10P
12	10N
13	9P
14	10M
15	11N
16	9M
17	9N
18	11L
19	11M
20	9L
21	10L
22	11K
23	10K
24	9J
25	9K
26	10J
27	11J
28	11H
29	10G
30	9G
31	11F
32	11G
33	9F
34	10F
35	11E
36	10E

6432 tbl 16

ORDER	PIN ID
37	10D
38	9E
39	10C
40	11D
41	9C
42	9D
43	11B
44	11C
45	9B
46	10B
47	11A
48	Internal
49	9A
50	8B
51	7C
52	6C
53	8A
54	7A
55	7B
56	6B
57	6A
58	5B
59	5A
60	4A
61	5C
62	4B
63	3A
64	1H
65	1A
66	2B
67	3B
68	1C
69	1B
70	3D
71	3C
72	1D

6432 tbl 17

ORDER	PIN ID
73	2C
74	3E
75	2D
76	2E
77	1E
78	2F
79	3F
80	1G
81	1F
82	3G
83	2G
84	1J
85	2J
86	3K
87	3J
88	2K
89	1K
90	2L
91	3L
92	1M
93	1L
94	3N
95	3M
96	1N
97	2M
98	3P
99	2N
100	2P
101	1P
102	3R
103	4R
104	4P
105	5P
106	5N
107	5R

6432 tbl 18

## JTAG DC Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit	Note
Output Power Supply	VDDQ	1.4	-	1.9	V	
Power Supply Voltage	VDD	1.7	1.8	1.9	V	
Input High Level	V <sub>IH</sub>	1.3	-	VDD + 0.3	V	
Input Low Level	V <sub>IL</sub>	- 0.3	-	0.5	V	
TCK Input Leakage Current	I <sub>IL</sub>	- 5	-	+ 5	uA	
TMS, TDI Input Leakage Current	I <sub>IL</sub>	- 15	-	+ 15	uA	
TDO Output Leakage Current	I <sub>OL</sub>	- 5	-	+ 5	uA	
Output High Voltage (IOH = -1mA)	VOH	VDDQ - 0.2	-	VDDQ	V	1
Output Low Voltage (IOL = 1mA)	VOL	VSS	-	0.2	V	1

**NOTE:**

6432 tbl 19

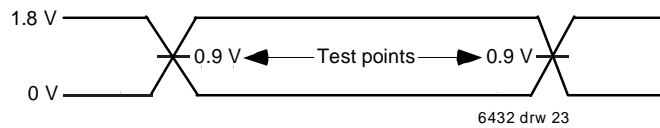
- The output impedance of TDO is set to 50 ohms (nominal process) and does not vary with the external resistor connected to ZQ.

## JTAG AC Test Conditions

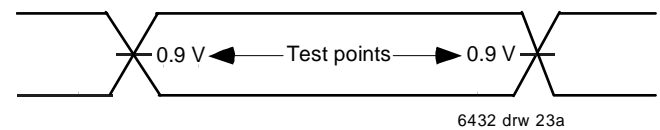
Parameter	Symbol	Min	Unit	Note
Input High Level	V <sub>IH</sub>	1.8	V	
Input Low Level	V <sub>IL</sub>	0	V	
Input Rise/Fall Time	TR/TF	1.0/1.0	ns	
Input and Output Timing Reference Level		0.9	V	1

Note: 1. For SRAM outputs see AC test output load on page 13. <sup>6432 tbl 20</sup>

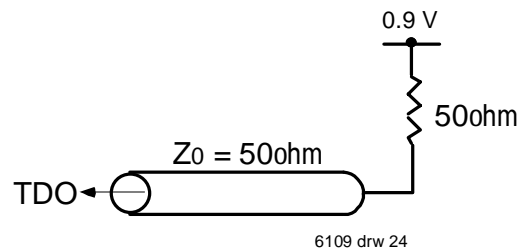
### JTAG Input Test WaveForm



### JTAG Output Test WaveForm



### JTAG AC Test Load

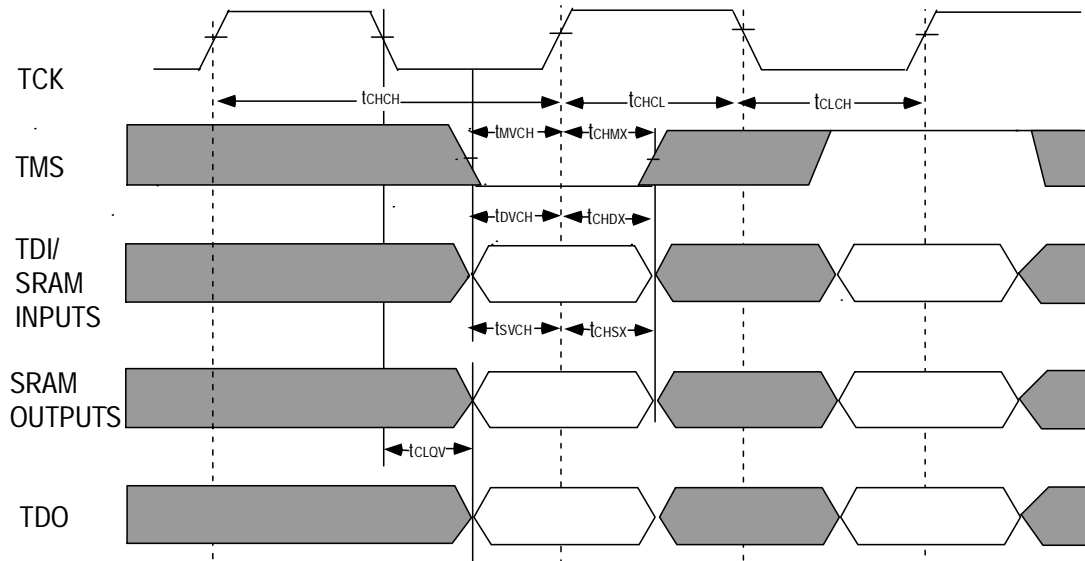


## JTAG AC Characteristics

Parameter	Symbol	Min	Max	Unit	Note
TCK Cycle Time	t <sub>CHCH</sub>	50	-	ns	
TCK High Pulse Width	t <sub>CHCL</sub>	20	-	ns	
TCK Low Pulse Width	t <sub>CLCH</sub>	20	-	ns	
TMS Input Setup Time	t <sub>MVCH</sub>	5	-	ns	
TMS Input Hold Time	t <sub>CHMX</sub>	5	-	ns	
TDI Input Setup Time	t <sub>DVCH</sub>	5	-	ns	
TDI Input Hold Time	t <sub>CHDX</sub>	5	-	ns	
SRAM Input Setup Time	t <sub>SVCH</sub>	5	-	ns	
SRAM Input Hold Time	t <sub>CHSX</sub>	5	-	ns	
Clock Low to Output Valid	t <sub>CLQV</sub>	0	10	ns	

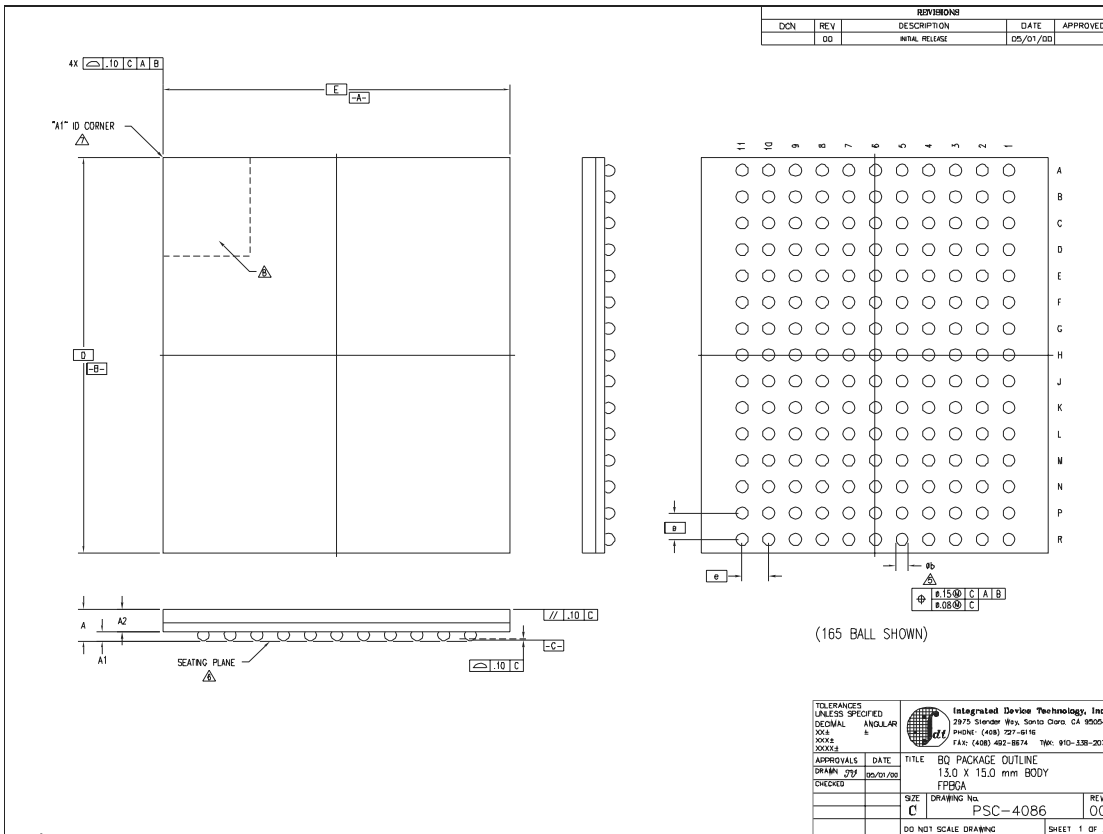
6432 tbl 21


## JTAG Timing Diagram

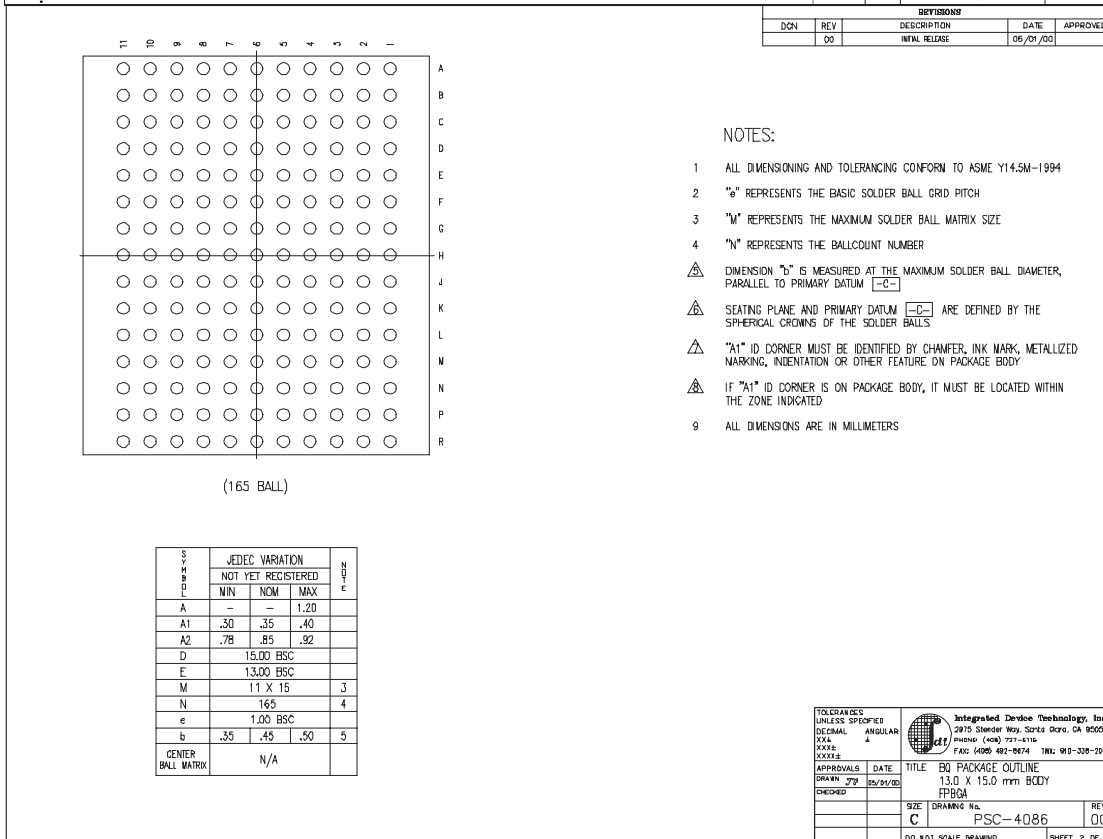






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# Package Diagram Outline for 165-Ball Fine Pitch Grid Array




TOLERANCES UNLESS SPECIFIED		 Integrated Device Technology, Inc. 2875 Stoner Way, Santa Clara, CA 95054 PHONE: (408) 727-6100 FAX: (408) 492-8674 TRN: 910-338-2070	
DECIMAL	ANGULAR		
XXX	°		
XXXX			
XXXXX			
APPROVALS	DATE	TITLE	REV
DRAWN JTP	05/21/00	BQ PACKAGE OUTLINE	00
CHECKED		13.0 X 15.0 mm BODY	
		FPCGA	
		SIZE C	DRAWING No. PSC-4086
		DO NOT SCALE DRAWING	SHEET 1 OF 2

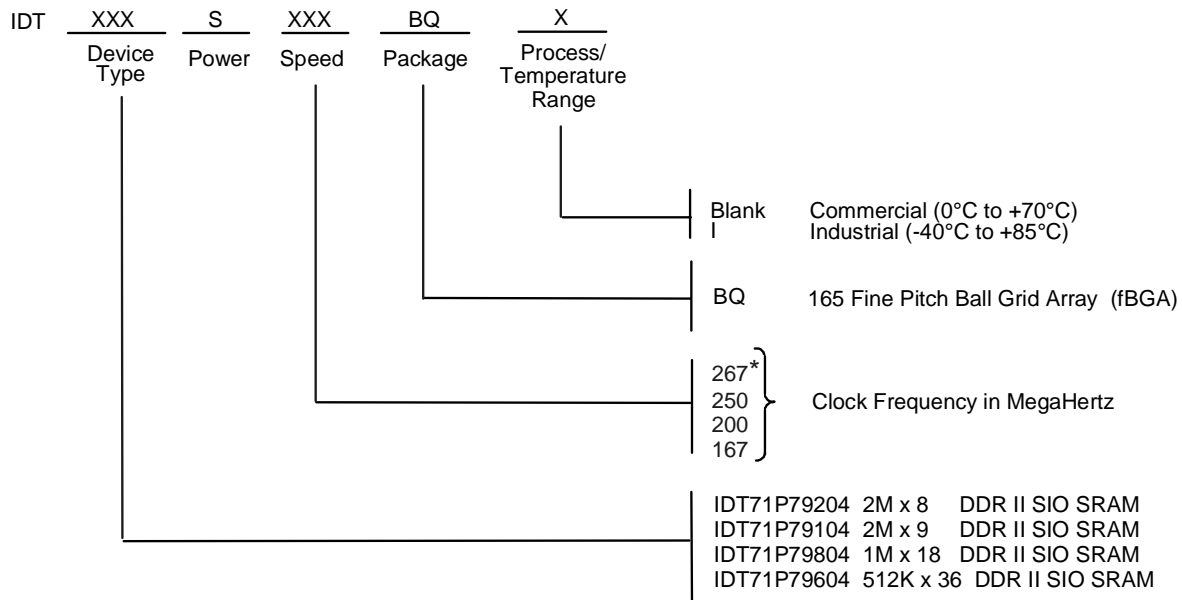


- NOTES:
- ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
  - "b" REPRESENTS THE BASIC SOLDER BALL PITCH
  - "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE
  - "N" REPRESENTS THE BALLCOUNT NUMBER
-  DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [-E-]
-  SEATING PLANE AND PRIMARY DATUM [-E-] ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
-  "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY
-  IF "A1" ID CORNER IS ON PACKAGE BODY, IT MUST BE LOCATED WITHIN THE ZONE INDICATED
- ALL DIMENSIONS ARE IN MILLIMETERS

SYMBOL	JEDEC VARIATION			N U M B E R
	NOT YET REGISTERED			
	MIN	NOM	MAX	
A	-	-	1.20	
A1	.30	.35	.40	
A2	.78	.85	.92	
D	15.00 BSC			
E	13.00 BSC			
M	11 X 15			3
N	165			4
e	1.00 BSC			
b	.35	.45	.50	5
CENTER BALL MATRIX	N/A			

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DECIMAL	ANGULAR		
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APPROVALS	DATE	TITLE	REV
DRAWN JTP	05/21/00	BQ PACKAGE OUTLINE	00
CHECKED		13.0 X 15.0 mm BODY	
		FPCGA	
		SIZE C	DRAWING No. PSC-4086
		DO NOT SCALE DRAWING	SHEET 2 OF 2

## Ordering Information



\* Only offered in the x18 option.

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 QDR SRAMs and Quad Data Rate RAMs comprise a new family of products developed by Cypress Semiconductor, IDT, and Micron Technology, Inc.

## Revision History

<u>REV</u>	<u>DATE</u>	<u>PAGES</u>	<u>DESCRIPTION</u>
0	07/26/05	p. 1-21	Released Final datasheet
1	11/30/05	p. 11,14,22	Added 267MHz speed grade to the DC and AC Electrical Characteristics tables and ordering information.